# Method and device for the transfer of components

The invention relates to a method for the transfer of, in particular electronic, components from a sender substrate to a receiver substrate.

The prior art shows the most diverse methods for transferring a product substrate from one carrier substrate to another carrier substrate. Such carrier exchange processes are mentioned in detail for example in publication WO2011120537A1. In recent years, individual functional components are increasingly being stacked above one another or beside one another. It is of crucial importance here that only those components are transferred which have passed a previous, in particular electrical, test. This thus eliminates the possibility of defective components being transferred.

Embodiments of the present invention provide a method and a device which at least partially eliminate, in particular completely eliminate the drawbacks stated in the prior art. In particular, embodiments of the invention provide an improved method and a device for transferring components from a sender substrate to a receiver substrate. Embodiments of the invention provide an improved method and a device for the production of a light-emitting diode, with which the individual components are transferred from a sender substrate to a receiver substrate. Embodiments of the invention provide a method and a device, with which no defective components or only components with specific properties are transferred to the receiver substrate.

According to a first aspect of the present invention, there is provided a method for the transfer of components from a sender substrate to a receiver substrate with at least the following steps, in particular with the following sequence: i) provision and/or production of the components on the sender substrate, ii) transfer of the components of the sender substrate to the transfer substrate, iii) transfer of the components from the transfer substrate to the receiver substrate, wherein the components can be transferred selectively by means of bonding means and/or debonding means.

According to a second aspect of the present invention, there is provided a device for the transfer of components using the above method, wherein components can be produced and/or provided on a sender substrate, and wherein the components of the sender substrate can be transferred to a transfer substrate, and wherein the components can be transferred from the transfer substrate to the receiver substrate, and wherein the transfer of the components to the transfer substrate and/or the receiver substrate can be carried out selectively by bonding means and/or debonding means.

According to a third aspect of the present invention, there is provided a light-emitting diode (LED) produced by the above method.

All combinations of at least two features indicated in the description, in the claims and/or the drawings also fall within the scope of the invention. In stated value ranges, values lying inside the stated limits should also be deemed to be disclosed as limiting values and can be claimed in any combination. In the subsequent text, a component is understood to mean an object to be transferred. A component does not necessarily have to have a functionality as such.